

# SN54S124, SN74S124 DUAL VOLTAGE-CONTROLLED OSCILLATORS

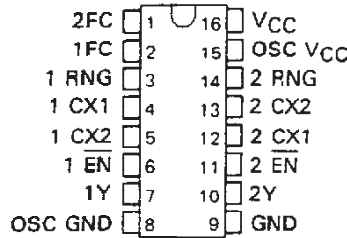
SDLS201A – DECEMBER 1983 – REVISED APRIL 2004

- Two independent VCOs in a 16-Pin Package
- Output Frequency Set by Single External Component:  
Capacitor for Fixed- or Variable-Frequency Operation
- Separate Supply Voltage Pins for Isolation of Frequency Control Inputs and Oscillators from Output Circuitry
- Highly Stable Operation over Specified Temperature and/or Supply Voltage Ranges
- Typical  $f_{max}$  . . . . . 85 MHz  
Typical Power Dissipation . . . . . 525 mW
- Frequency Spectrum . . . 1 Hz to 60 MHz

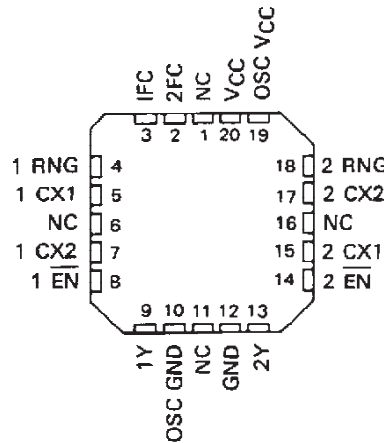
## description

The 'S124 features two independent voltage-controlled oscillators (VCO) in a single monolithic chip. The output frequency of each VCO is established by an external capacitor in combination with two voltage-sensitive inputs, one for frequency range and one for frequency control. These inputs can be used to vary the output frequency as shown under typical characteristics. These highly stable oscillators can be set to operate at any frequency typically between 0.12 hertz and 85 megahertz. 1

SN54S124 . . . J OR W PACKAGE  
SN74S124 . . . D OR N PACKAGE  
(TOP VIEW)



SN54S124 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

While the enable input is low, the output is enabled.  
While the enable input is high, the output is high.

These devices can operate from a single 5-volt supply. However, one set of supply-voltage and ground pins ( $V_{CC}$  and  $GND$ ) is provided for the enable, synchronization-gating, and output sections, and a separate set ( $\ominus V_{CC}$  and  $\ominus GND$ ) is provided for the oscillator and associated frequency-control circuits so that effective isolation can be accomplished in the system.

The enable input of these devices starts or stops the output pulses when it is low or high, respectively. The internal oscillator of the 'S124 is started and stopped by the enable input. The enable input is one standard load; it and the buffered output operate at standard Schottky-clamped TTL levels.

The pulse synchronization-gating section ensures that the first output pulse is neither clipped nor extended. Duty cycle of the square-wave output is fixed at approximately 50 percent.

The SN54S124 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ ; the SN74S124 is characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

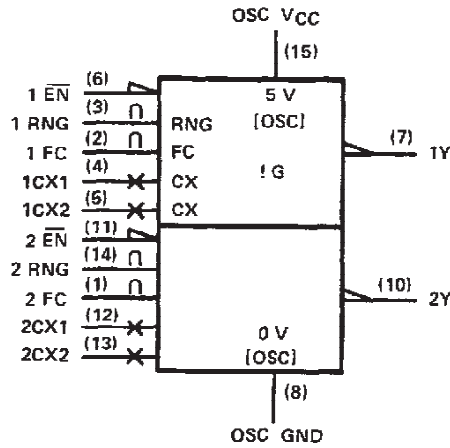
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2004, Texas Instruments Incorporated

# SN54S124, SN74S124 DUAL VOLTAGE-CONTROLLED OSCILLATORS

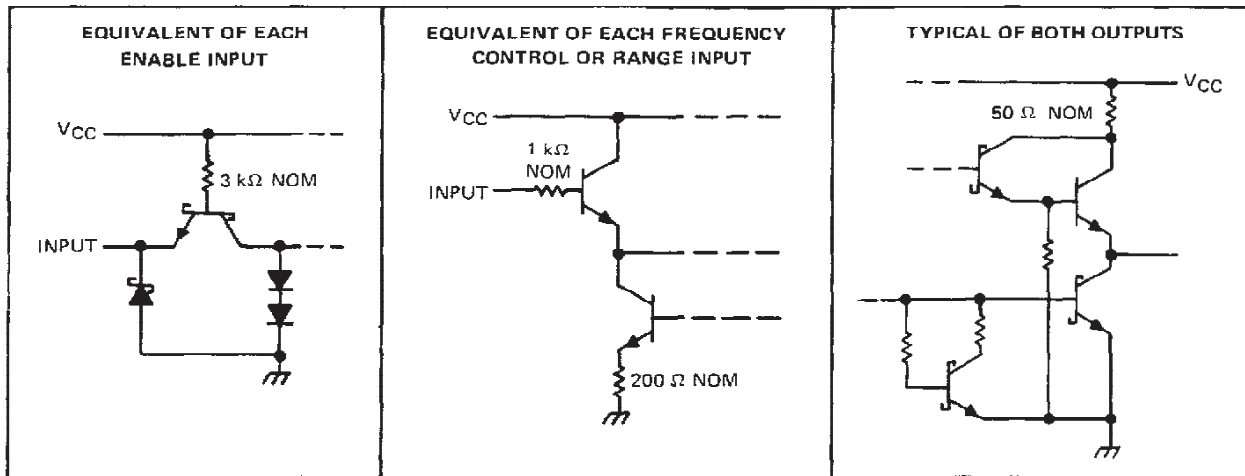
SDLS201A – DECEMBER 1983 – REVISED APRIL 2004

## logic symbol†



†This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

## schematics of inputs and outputs



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (See Notes 1 and 2)	7V
Input voltage	5.5 V
Operating free-air temperature range: SN54S124	-55°C to 125°C
SN74S124	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTES: 1. Voltage values are with respect to the appropriate ground terminal.

2. Throughout this data sheet, the symbol  $V_{CC}$  is used for the voltage applied to both the  $V_{CC}$  and  $\odot V_{CC}$  terminals, unless otherwise noted.

# SN54S124, SN74S124 DUAL VOLTAGE-CONTROLLED OSCILLATORS

SDLS201A – DECEMBER 1983 – REVISED APRIL 2004

## recommended operating conditions

	SN54S124			SN74S124			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, $V_{CC}$ (see Note 1)	4.5	5	5.5	4.75	5	6.25	V
Input voltage at frequency control or range input, $V_{I(freq)}$ or $V_{I(rng)}$	1		5	1		5	V
High-level output current, $I_{OH}$			-1			-1	mA
Low-level output current, $I_{OL}$			20			20	mA
Output frequency (enabled), $f_o$	1			1			Hz
			60			60	MHz
Operating free-air temperature, $T_A$	-55		125	0		70	$^{\circ}$ C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT	
$V_{IH}$	High-level input voltage at enable		2			V	
$V_{IL}$	Low-level input voltage at enable				0.8	V	
$V_{IK}$	Input clamp voltage at enable	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			-1.2	V	
$V_{OH}$	High-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, I_{OH} = -1 \text{ mA}$	SN54S'	2.5	3.4	V	
			SN74S'	2.7	3.4		
$V_{OL}$	Low-level output voltage	$V_{CC} = \text{MIN}, V_{IL} = 0.8 \text{ V}, I_{OL} = 20 \text{ mA}$			0.5	V	
$I_I$	Input current	Freq control or range	$V_{CC} = \text{MAX}$	$V_I = 5 \text{ V}$	10	50	$\mu$ A
				$V_I = 1 \text{ V}$	1	15	
$I_I$	Input current at maximum input voltage	Enable	$V_{CC} = \text{MAX}, V_I = 5.5 \text{ V}$		1	mA	
$I_{IH}$	High-level input current	Enable	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$		50	$\mu$ A	
$I_{IL}$	Low-level input current	Enable	$V_{CC} = \text{MAX}, V_I = 0.5 \text{ V}$		-2	mA	
$I_{OS}$	Short-circuit output current §	$V_{CC} = \text{MAX}$	-40		-100	mA	
$I_{CC}$	Supply current, total into $V_{CC}$ and $\ominus V_{CC}$	$V_{CC} = \text{MAX}, \text{ See Note 3}$		105	150	mA	
		$V_{CC} = \text{MAX}, T_A = 125^{\circ}\text{C}, \text{ W package only}$ See Note 3			110		

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at  $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$ .

§Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

NOTE 3:  $I_{CC}$  is measured with the outputs disabled and open.

## switching characteristics, $V_{CC} = 5 \text{ V}, R_L = 280 \Omega, C_L = 15 \text{ pF}, T_A = 25^{\circ}\text{C}$ (see note 4)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$f_o$	Output frequency	$C_{ext} = 2 \text{ pF}$	$V_{I(freq)} = 4 \text{ V}, V_{I(rng)} = 1 \text{ V}$	60	85	MHz
			$V_{I(freq)} = 1 \text{ V}, V_{I(rng)} = 5 \text{ V}$	25	40	
	Output duty cycle	$C_{ext} = 8.3 \text{ pF}$ to $500 \mu\text{F}$		50%		
$t_{PHL}$	Propagation delay time, high-to-low-level output from enable	$f_o = 1 \text{ Hz}$ to $20 \text{ MHz}$		$\frac{1.4}{f_o(\text{Hz})}$		s
		$f_o > 20 \text{ MHz}$		70		ns

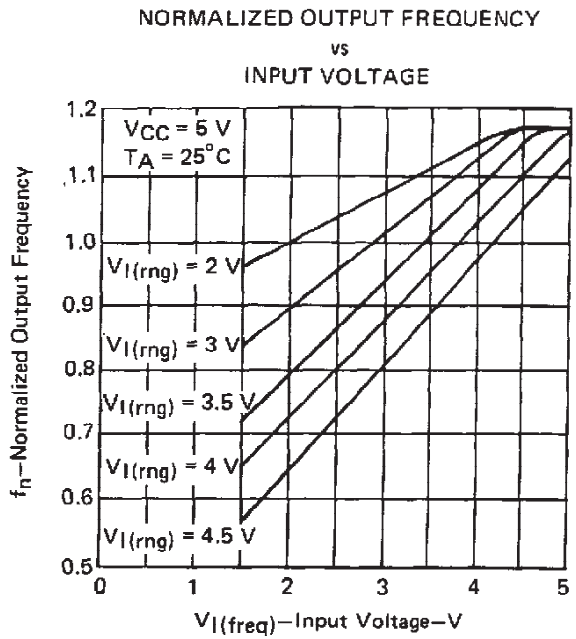
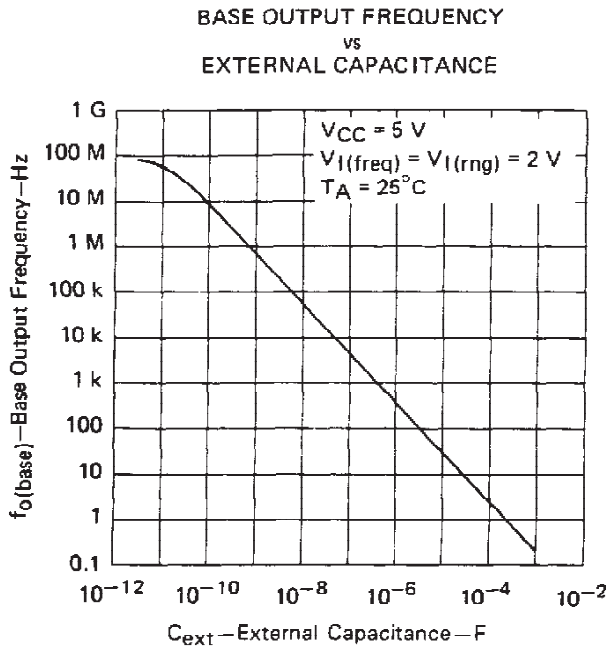
NOTE 4: Load circuits and voltage waveforms are shown in Section 1.



# SN54S124, SN74S124 DUAL VOLTAGE-CONTROLLED OSCILLATORS

SDLS201A - DECEMBER 1983 - REVISED APRIL 2004

## TYPICAL CHARACTERISTICS



NOTE:  $f_o = f_n \times f_{o(\text{base})}$

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN54S124J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN74S124D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S124DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S124DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S124N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S124N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S124NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54S124J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54S124W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



4040180-3/D 07/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)